Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

DA3J104F

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
  (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 32

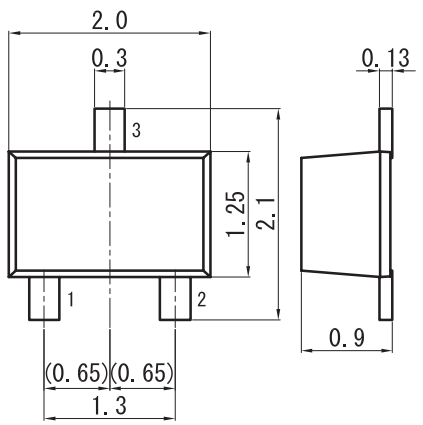
■ Basic Part Number

Dual DA2J104 (Series)

■ Packaging

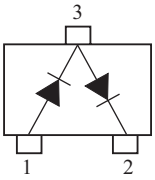
DA3J104F0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Unit: mm



1: Anode-1 3: Cathode-1
2: Cathode-2 Anode-2

Panasonic	SMini3-F2-B
JEITA	SC-85
Code	—



■ Absolute Maximum Ratings $T_a = 25°C$

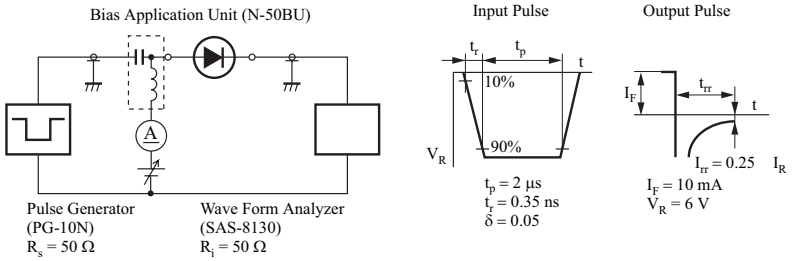
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Maximum peak reverse voltage		V_{RM}	80	V
Forward current	Single	I_F	200	mA
	Series		130	mA
Peak forward current	Single	I_{FM}	600	mA
	Series		385	mA
Non-repetitive peak forward surge current *1	Single	I_{FSM}	1.0	A
	Series		0.7	A
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) *1: t = 1 s

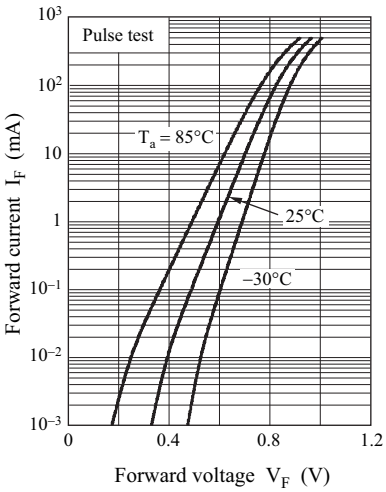
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA		0.90	1.10	V
Reverse voltage	V_R	I_R = 100 μA	80			V
Reverse current	I_R	V_R = 80 V			500	nA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz			4.0	pF
Reverse recovery time *1	t_{rr}	I_F = 10 mA, V_R = 6 V, I_{rr} = 0.25 × I_R			10	ns

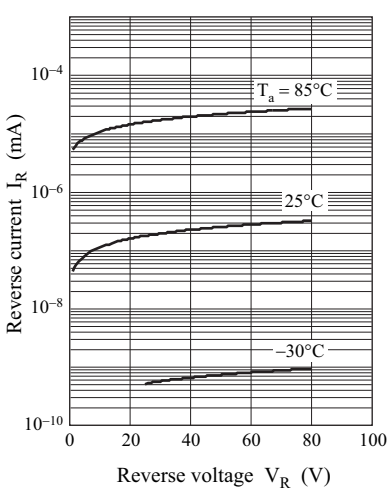
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz
3. *1: t_{rr} measurement circuit



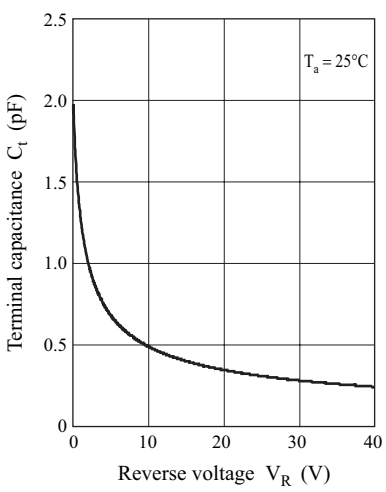
I_F — V_F



I_R — V_R

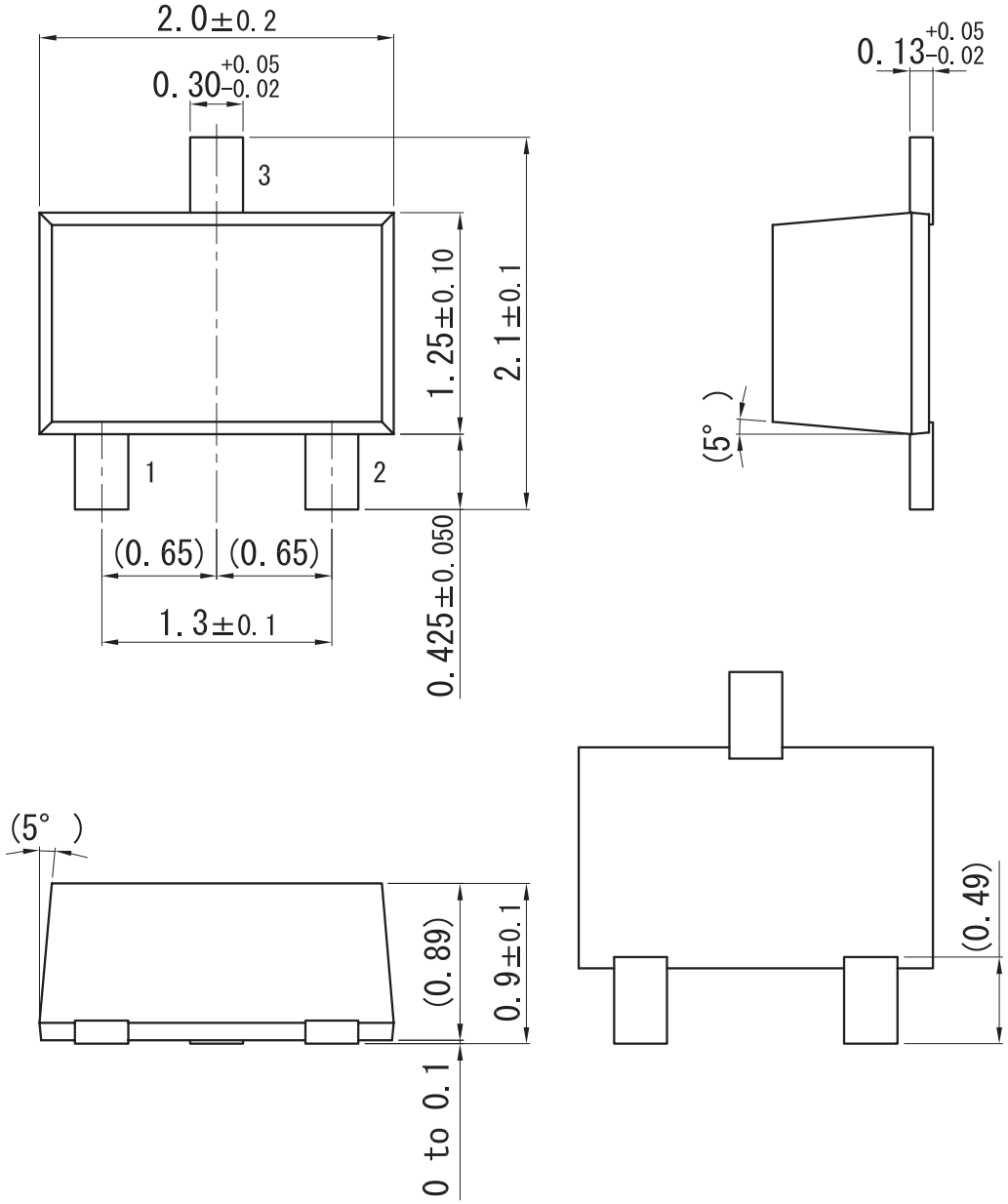


C_t — V_R

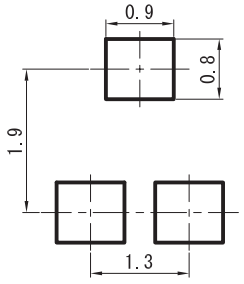


SMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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